

HIGH NOISE REDUCTION, HIGH SPEED DIGITAL OUTPUT TYPE
8-PIN DIP PHOTOCOUPLER

–NEPOC Series–

DESCRIPTION

The PS9614 and PS9614L are optically coupled isolators containing a GaAlAs LED on the input side and a photo diode and a signal processing circuit on the output side on one chip.

The PS9614 is in a plastic DIP (Dual In-line Package) and the PS9614L is lead bending type (Gull-wing) for surface mounting.

FEATURES

- High common mode transient immunity (CM_H , $CM_L = \pm 20 \text{ kV}/\mu\text{s}$ TYP.)
- High isolation voltage ($BV = 3\,750 \text{ V r.m.s.}$)
- High-speed response (10 Mbps)
- Pulse width distortion ($|t_{PHL} - t_{PLH}| = 10 \text{ ns}$ TYP.)
- Open collector output
- Ordering number of tape product: PS9614L-E3, E4: 1 000 pcs/reel
- Safety standards
 - UL approved: File No. E72422 (S)
 - VDE0884 approved (Option) : No.91877

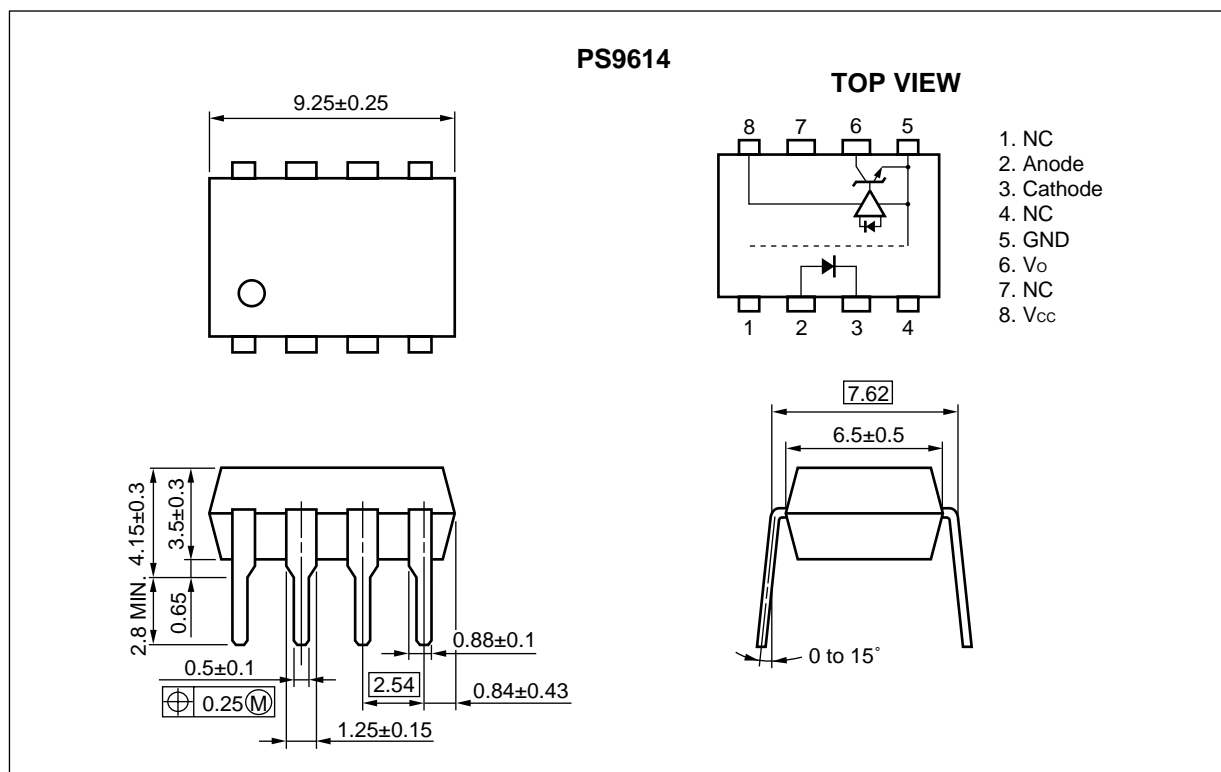
APPLICATIONS

- FA Network
- Measurement equipment
- PDP

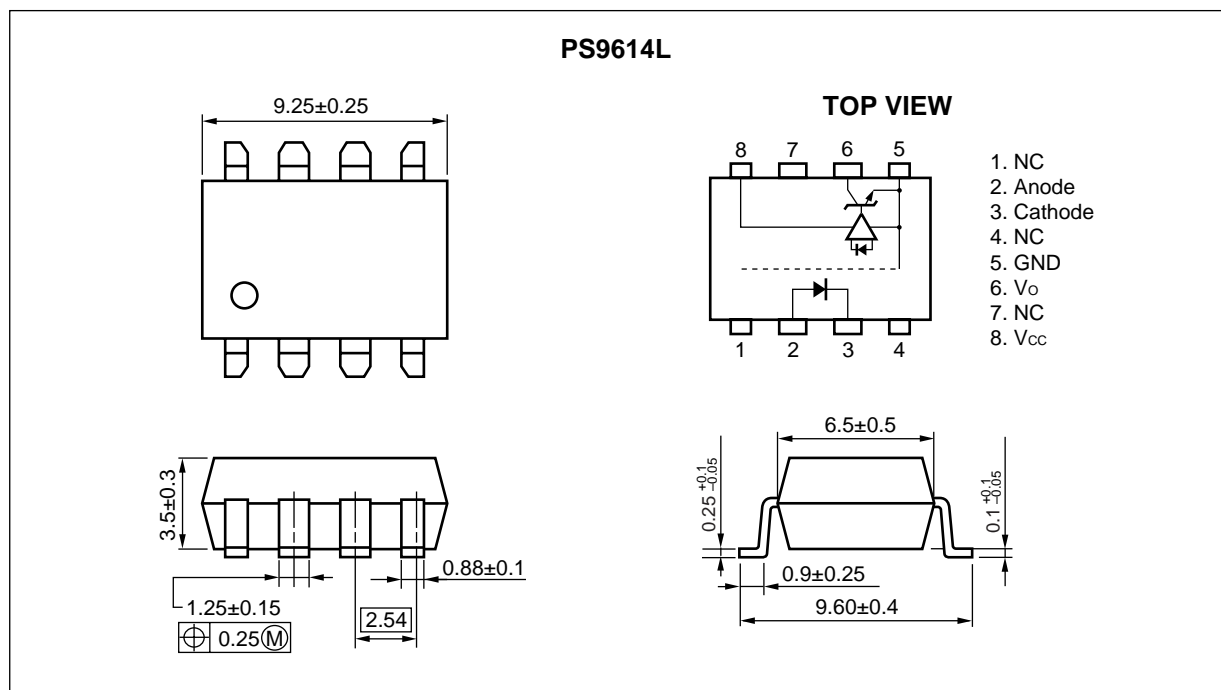
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★ PACKAGE DIMENSIONS (UNIT: mm)

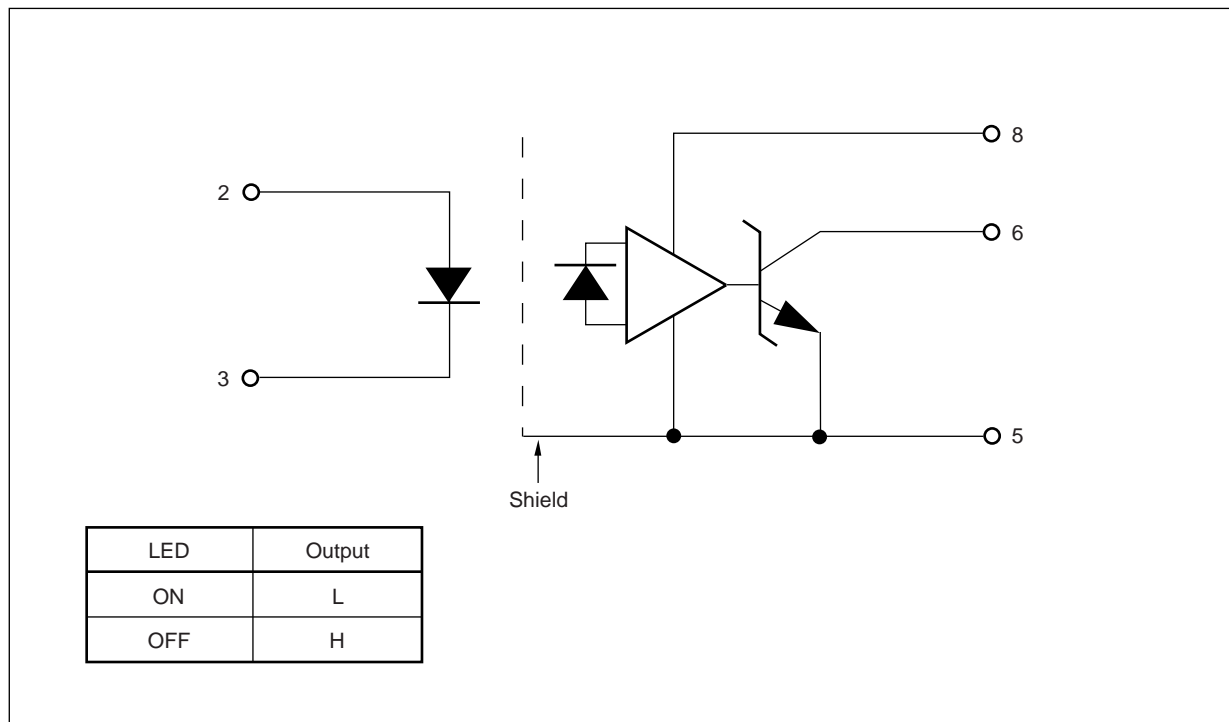
DIP Type



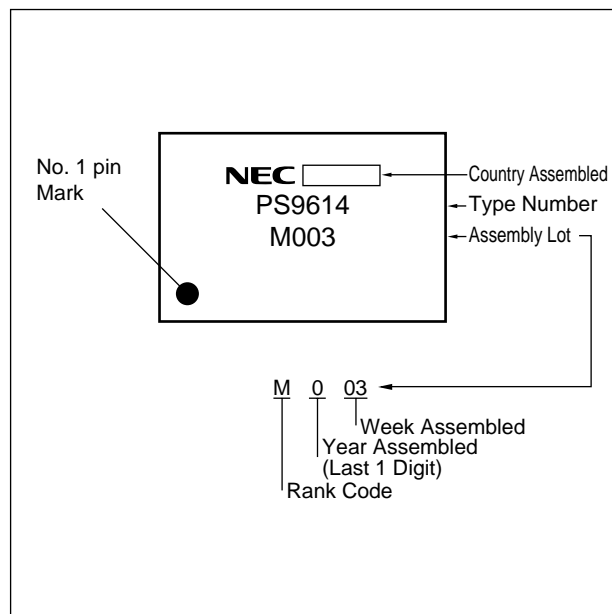
Lead Bending Type



FUNCTIONAL DIAGRAM



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Package	Packing Style	Safety Standards Approval	Application Part Number ^{*1}
PS9614	8-pin DIP	Magazine case 50 pcs	Approved products other than VDE	PS9614
PS9614L				PS9614L
PS9614L-E3		Embossed Tape 1 000 pcs/reel		
PS9614L-E4				
PS9614-V		Magazine case 50 pcs	VDE0884 approved (Option)	PS9614
PS9614L-V				PS9614L
PS9614L-V-E3		Embossed Tape 1 000 pcs/reel		
PS9614L-V-E4				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I _F	30	mA
	Reverse Voltage	V _R	3	V
Detector	Supply Voltage	V _{CC}	7	V
	Output Voltage	V _O	7	V
	Output Current	I _O	25	mA
	Power Dissipation ^{*1}	P _C	40	mW
Isolation Voltage ^{*2}		BV	3 750	Vr.m.s.
Operating Ambient Temperature		T _A	−40 to +85	°C
Storage Temperature		T _{stg}	−55 to +125	°C

*1 Applies to output pin V_O.

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.

RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

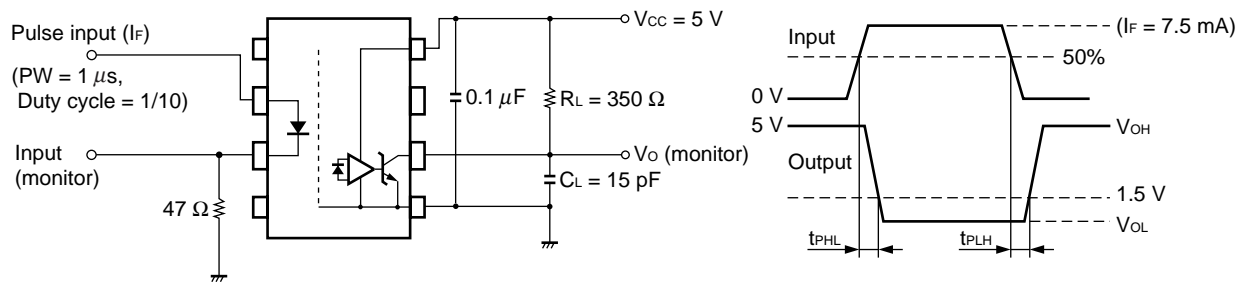
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
High Level Input Current	I _{FH}	6.3	10	12.5	mA
Low Level Input Voltage	V _{FL}	0		0.8	V
Supply Voltage	V _{CC}	4.5	5.0	5.5	V
TTL (R _L = 1 kΩ, loads)	N			5	
Pull-up Resistance	R _L	330		4 k	Ω
Operating Ambient Temperature	T _A	−40		+85	°C

ELECTRICAL CHARACTERISTICS ($T_A = -40$ to $+85^\circ\text{C}$, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP. ¹⁾	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 10\text{ mA}$, $T_A = 25^\circ\text{C}$	1.4	1.65	1.9	V
	Reverse Current	I_R	$V_R = 3\text{ V}$, $T_A = 25^\circ\text{C}$			10	μA
	Terminal Capacitance	C_t	$V = 0\text{ V}$, $f = 1\text{ MHz}$, $T_A = 25^\circ\text{C}$		30		pF
Detector	High Level Output Current	I_{OH}	$V_{CC} = V_O = 5.5\text{ V}$, $V_F = 0.8\text{ V}$		0.03	250	μA
	Low Level Output Voltage	V_{OL}	$V_{CC} = 5.5\text{ V}$, $I_F = 5\text{ mA}$, $I_{OL} = 13\text{ mA}$		0.2	0.6	V
	High Level Supply Current	I_{CCH}	$V_{CC} = 5.5\text{ V}$, $I_F = 0\text{ mA}$		2.6	8	mA
	Low Level Supply Current	I_{CCL}	$V_{CC} = 5.5\text{ V}$, $I_F = 10\text{ mA}$		7	11	mA
Coupled	Threshold Input Current	I_{FHL}	$V_{CC} = 5\text{ V}$, $V_O = 0.8\text{ V}$, $R_L = 350\ \Omega$		2.3	5	mA
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1\text{ kV}_{DC}$, $R_H = 40$ to 60% , $T_A = 25^\circ\text{C}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}$, $f = 1\text{ MHz}$, $T_A = 25^\circ\text{C}$		0.9		pF
	Propagation Delay Time ($H \rightarrow L$) ²⁾	t_{PHL}	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ $R_L = 350\ \Omega$, $I_F = 7.5\text{ mA}$, $C_L = 15\text{ pF}$		61	75	ns
						100	
	Propagation Delay Time ($L \rightarrow H$) ²⁾	t_{PLH}	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ $R_L = 350\ \Omega$, $I_F = 7.5\text{ mA}$, $C_L = 15\text{ pF}$		51	75	ns
						100	
	Rise Time	t_r	$V_{CC} = 5\text{ V}$, $R_L = 350\ \Omega$, $I_F = 7.5\text{ mA}$, $C_L = 15\text{ pF}$		20		ns
	Fall Time	t_f			8		ns
	Pulse Width Distortion (PWD) ²⁾	$ t_{PHL} - t_{PLH} $			10	50	ns
	Propagation Delay Skew	t_{PSK}				60	ns
	Common Mode Transient Immunity at High Level Output ³⁾	CM_H	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $I_F = 0\text{ mA}$, $V_{O(MIN)} = 2\text{ V}$, $V_{CM} = 1\text{ kV}$, $R_L = 350\ \Omega$	10	20		kV/ μs
	Common Mode Transient Immunity at Low Level Output ³⁾	CM_L	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $I_F = 7.5\text{ mA}$, $V_{O(MAX)} = 0.8\text{ V}$, $V_{CM} = 1\text{ kV}$, $R_L = 350\ \Omega$	10	20		kV/ μs

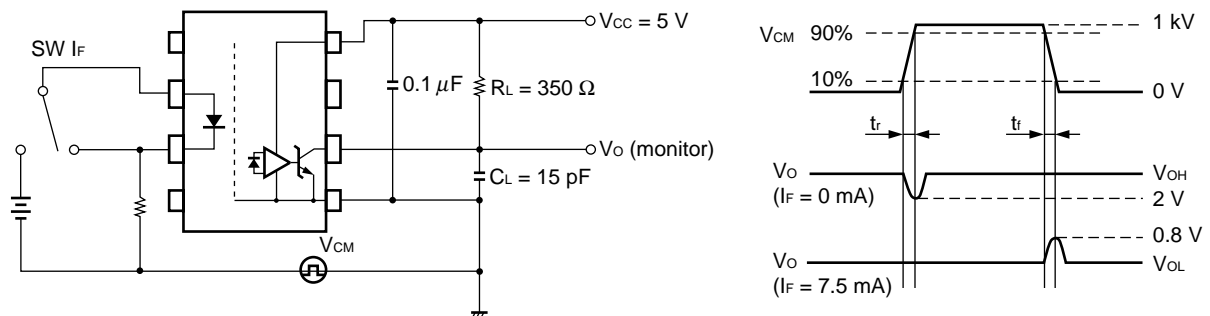
*1 Typical values at $T_A = 25^\circ\text{C}$

*2 Test circuit for propagation delay time



C_L includes probe and stray wiring capacitance.

*3 Test circuit for common mode transient immunity



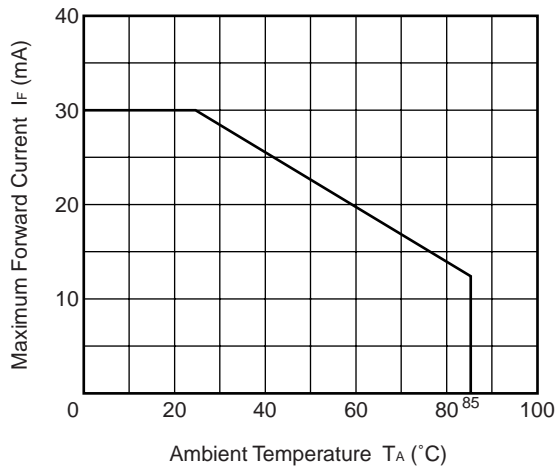
C_L includes probe and stray wiring capacitance.

USAGE CAUTIONS

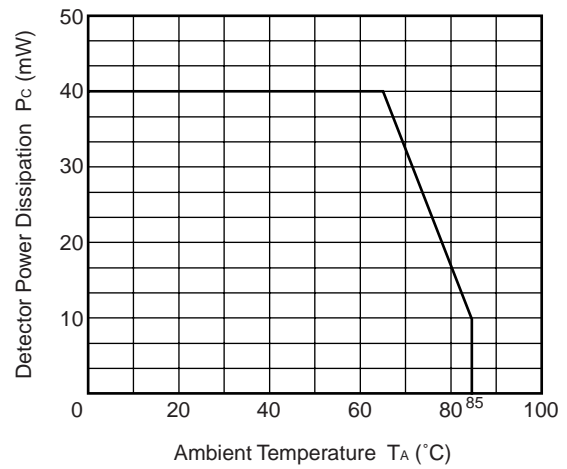
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than $0.1\ \mu\text{F}$ is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than $10\ \text{mm}$.
- ★ 3. Avoid storage at a high temperature and high humidity.

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

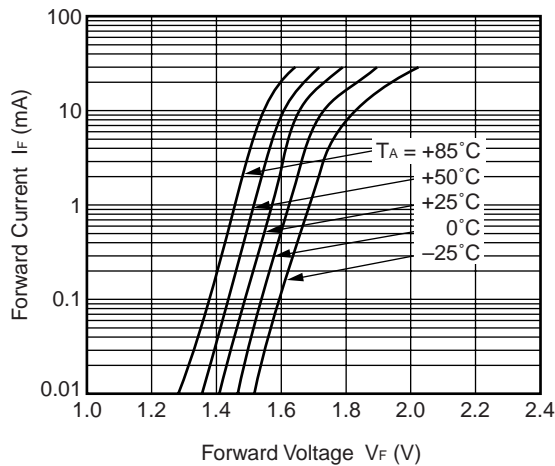
**MAXIMUM FORWARD CURRENT
vs. AMBIENT TEMPERATURE**



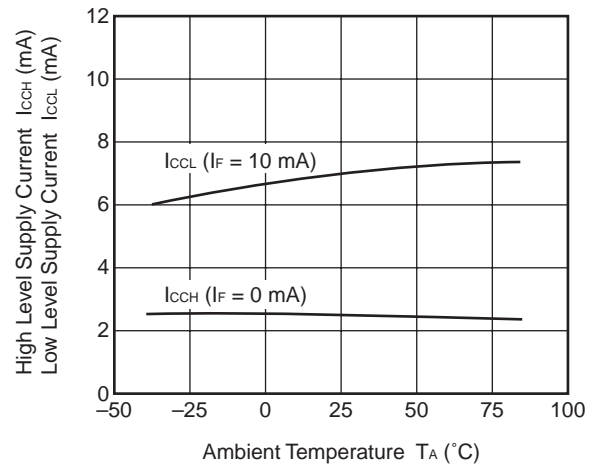
**DETECTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE**



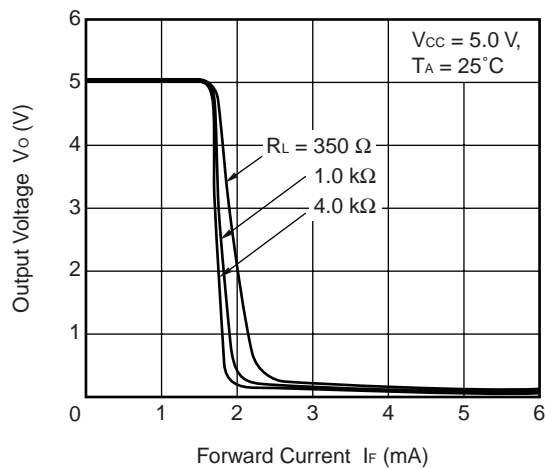
**FORWARD CURRENT vs.
FORWARD VOLTAGE**



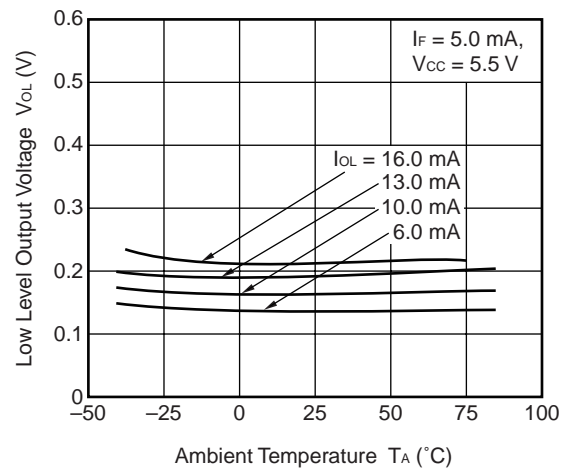
**SUPPLY CURRENT vs.
AMBIENT TEMPERATURE**



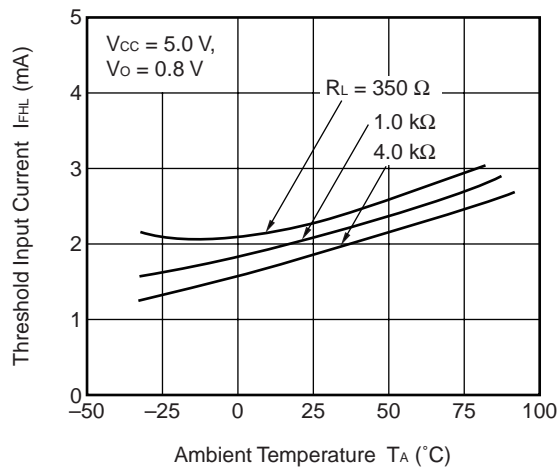
**OUTPUT VOLTAGE vs.
FORWARD CURRENT**



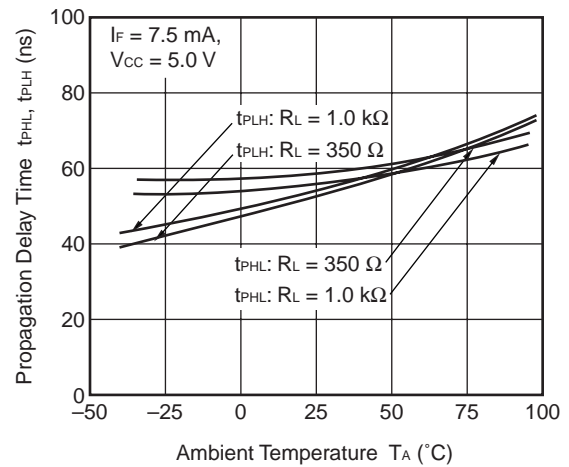
**LOW LEVEL OUTPUT VOLTAGE vs.
AMBIENT TEMPERATURE**



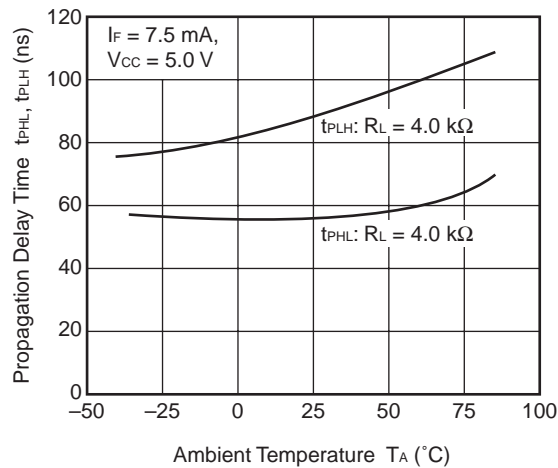
THRESHOLD INPUT CURRENT vs.
AMBIENT TEMPERATURE



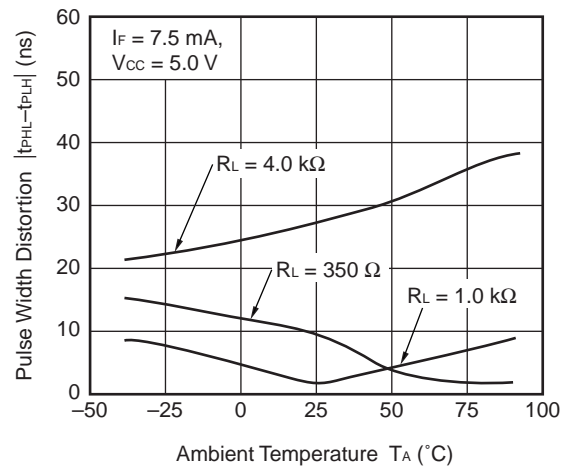
PROPAGATION DELAY TIME vs.
AMBIENT TEMPERATURE



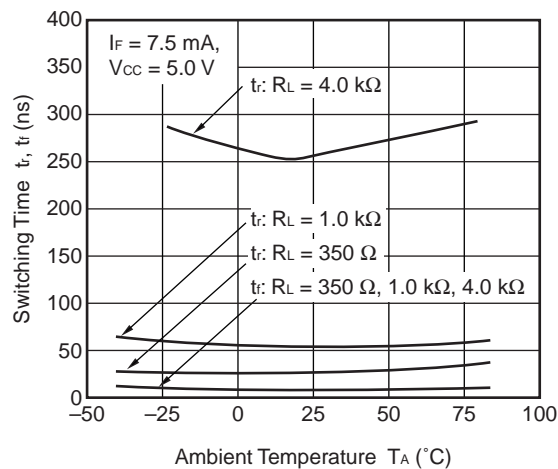
PROPAGATION DELAY TIME vs.
AMBIENT TEMPERATURE



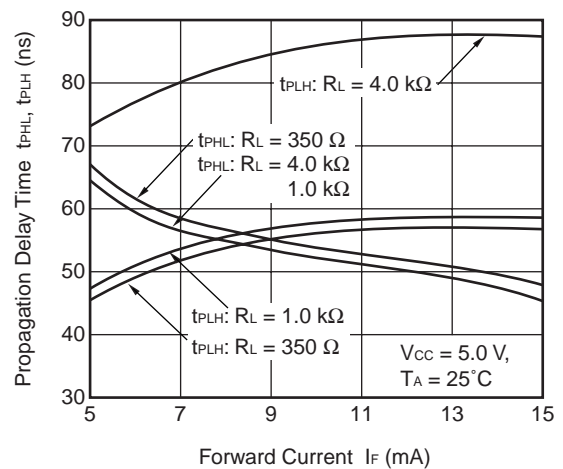
PULSE WIDTH DISTORTION vs.
AMBIENT TEMPERATURE



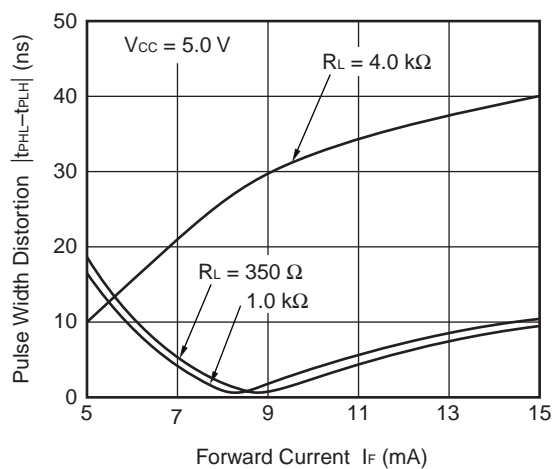
SWITCHING TIME vs.
AMBIENT TEMPERATURE



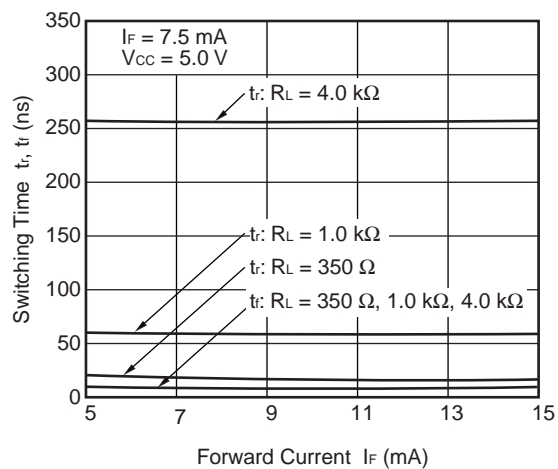
PROPAGATION DELAY TIME vs.
FORWARD CURRENT



PULSE WIDTH DISTORTION vs.
FORWARD CURRENT



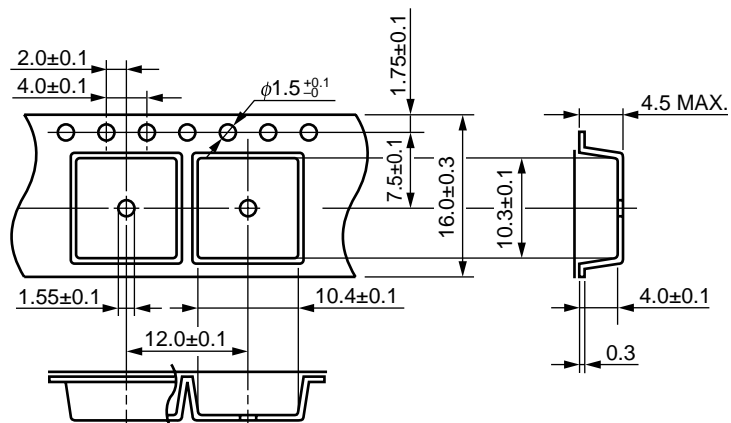
SWITCHING TIME vs.
FORWARD CURRENT



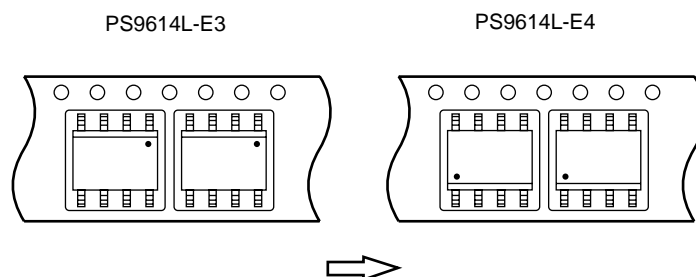
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (UNIT: mm)

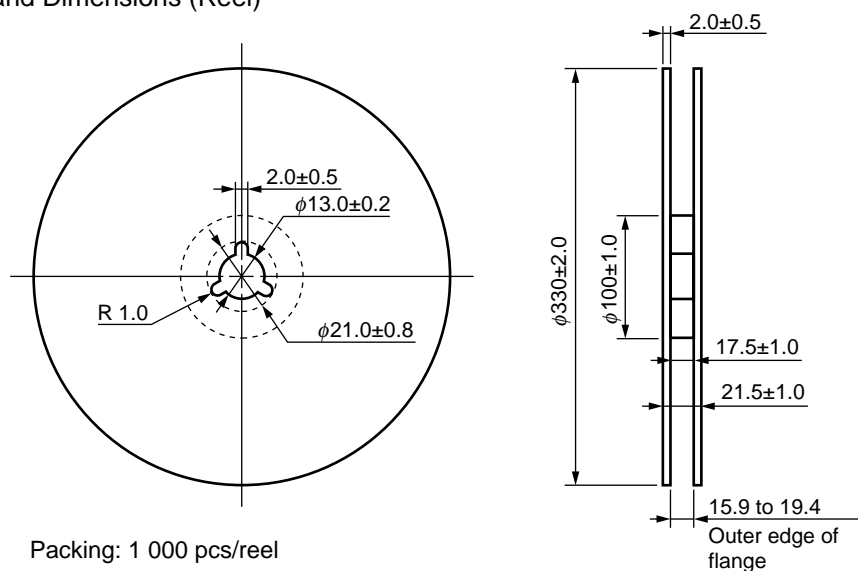
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

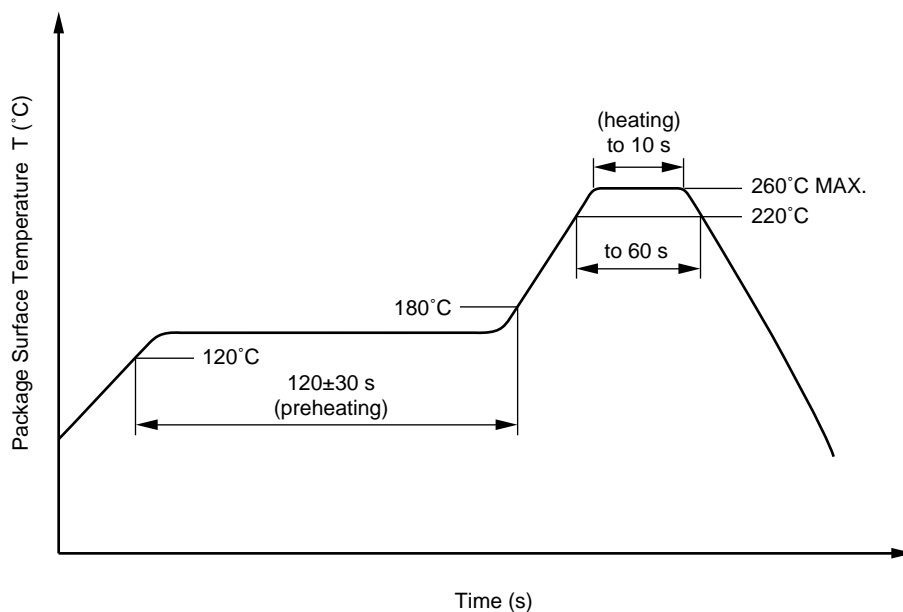
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

★ 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output side may enter the on state, even if the voltage is within the absolute maximum ratings.

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

<div data-bbox="177 271 288 315" data-label="Section-Header"> <p>Caution</p> </div> <p>GaAs Products</p>	<p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p>
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► For further information, please contact

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